

# Modeling in the Electronics Industry: The role of Pd in electroless copper deposition

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Palladium is an important ingredient in today's plating baths. It is used as a catalyst to initiate the deposition of copper from aqueous solution. However, the underlying mechanism is still not clear. Based on density functional theory, we performed calculations of Pd nano cluster and surfaces in the presence of cupric ions and additives such as formaldehyde.